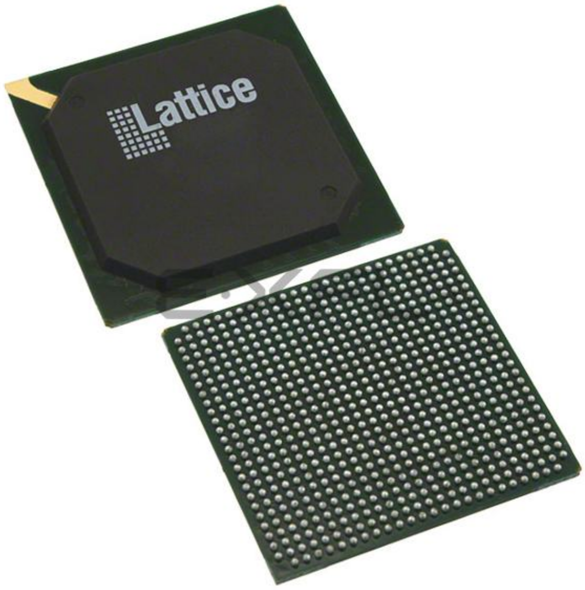

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	32800
Total RAM Bits	434176
Number of I/O	496
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FPBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfecp33e-3fn672c

LatticeECP/EC Family Data Sheet
Introduction

September 2012 **Data Sheet**

Features

- **Extensive Density and Package Options**
  - 1.5K to 32.8K LUT4s
  - 65 to 496 I/Os
  - Density migration supported
- **sysDSP™ Block (LatticeECP™ Versions)**
  - High performance multiply and accumulate
  - 4 to 8 blocks
    - 4 to 8 36x36 multipliers or
    - 16 to 32 18x18 multipliers or
    - 32 to 64 9x9 multipliers
- **Embedded and Distributed Memory**
  - 18 Kbits to 498 Kbits sysMEM™ Embedded Block RAM (EBR)
  - Up to 131 Kbits distributed RAM
  - Flexible memory resources:
    - Distributed and block memory
- **Flexible I/O Buffer**
  - Programmable sysI/O™ buffer supports wide range of interfaces:
    - LVCMOS 3.3/2.5/1.8/1.5/1.2
    - LVTTL
    - SSTL 3/2 Class I, II, SSTL18 Class I
    - HSTL 18 Class I, II, III, HSTL15 Class I, III
    - PCI
    - LVDS, Bus-LVDS, LVPECL, RSDS
- **Dedicated DDR Memory Support**
  - Implements interface up to DDR400 (200MHz)
- **sysCLOCK™ PLLs**
  - Up to four analog PLLs per device
  - Clock multiply, divide and phase shifting
- **System Level Support**
  - IEEE Standard 1149.1 Boundary Scan, plus ispTRACY™ internal logic analyzer capability
  - SPI boot flash interface
  - 1.2V power supply
- **Low Cost FPGA**
  - Features optimized for mainstream applications
  - Low cost TQFP and PQFP packaging

Table 1-1. LatticeECP/EC Family Selection Guide

Device	LFEC1	LFEC3	LFEC6/ LFECP6	LFEC10/ LFECP10	LFEC15/ LFECP15	LFEC20/ LFECP20	LFEC33/ LFECP33
PFU/PFF Rows	12	16	24	32	40	44	64
PFU/PFF Columns	16	24	32	40	48	56	64
PFUs/PFFs	192	384	768	1280	1920	2464	4096
LUTs (K)	1.5	3.1	6.1	10.2	15.4	19.7	32.8
Distributed RAM (Kbits)	6	12	25	41	61	79	131
EBR SRAM (Kbits)	18	55	92	276	350	424	498
EBR SRAM Blocks	2	6	10	30	38	46	54
sysDSP Blocks[1]	—	—	4	5	6	7	8
18x18 Multipliers[1]	—	—	16	20	24	28	32
V_{CC} Voltage (V)	1.2	1.2	1.2	1.2	1.2	1.2	1.2
Number of PLLs	2	2	2	4	4	4	4
Packages and I/O Combinations:							
100-pin TQFP (14 x 14 mm)	67	67					
144-pin TQFP (20 x 20 mm)	97	97	97				
208-pin PQFP (28 x 28 mm)	112	145	147	147			
256-ball fpBGA (17 x 17 mm)		160	195	195	195		
484-ball fpBGA (23 x 23 mm)			224	288	352	360	360
672-ball fpBGA (27 x 27 mm)						400	496

[1] LatticeECP devices only.

Routing

There are many resources provided in the LatticeECP/EC devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU). The x1 and x2 connections provide fast and efficient connections in horizontal and vertical directions. The x2 and x6 resources are buffered, the routing of both short and long connections between PFUs.

The ispLEVER design tool suite takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

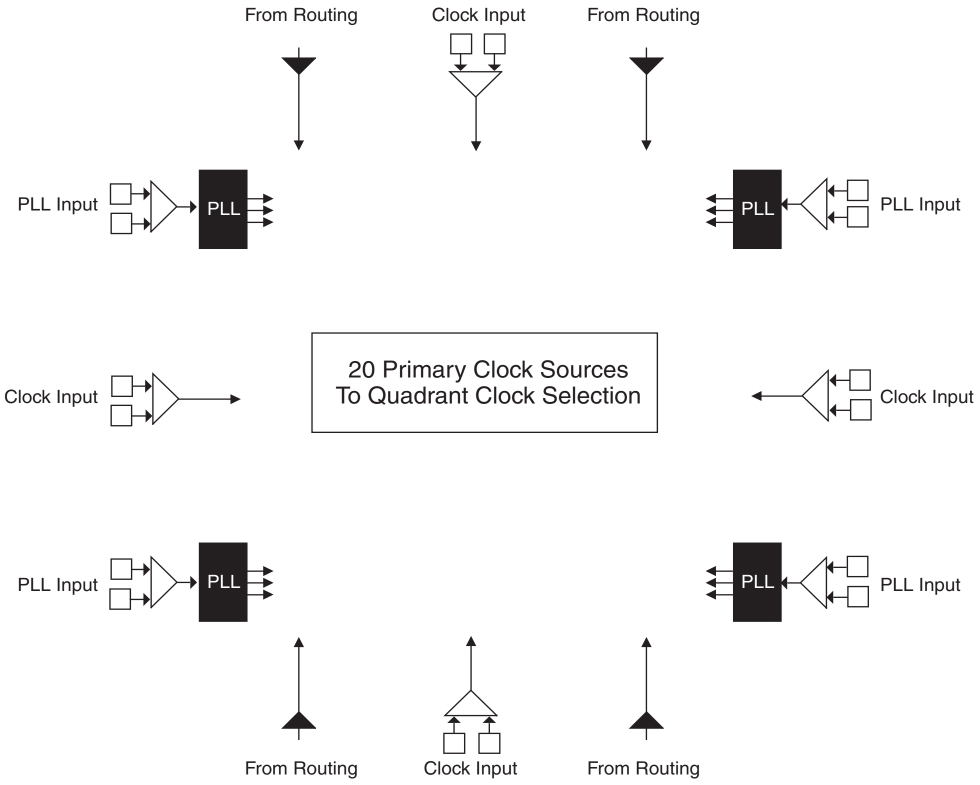
Clock Distribution Network

The clock inputs are selected from external I/O, the sysCLOCK™ PLLs or routing. These clock inputs are fed through the chip via a clock distribution system.

Primary Clock Sources

LatticeECP/EC devices derive clocks from three primary sources: PLL outputs, dedicated clock inputs and routing. LatticeECP/EC devices have two to four sysCLOCK PLLs, located on the left and right sides of the device. There are four dedicated clock inputs, one on each side of the device. Figure 2-6 shows the 20 primary clock sources.

Figure 2-6. Primary Clock Sources



Note: Smaller devices have two PLLs.

grammed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the t_{LOCK} parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

Figure 2-11. PLL Diagram

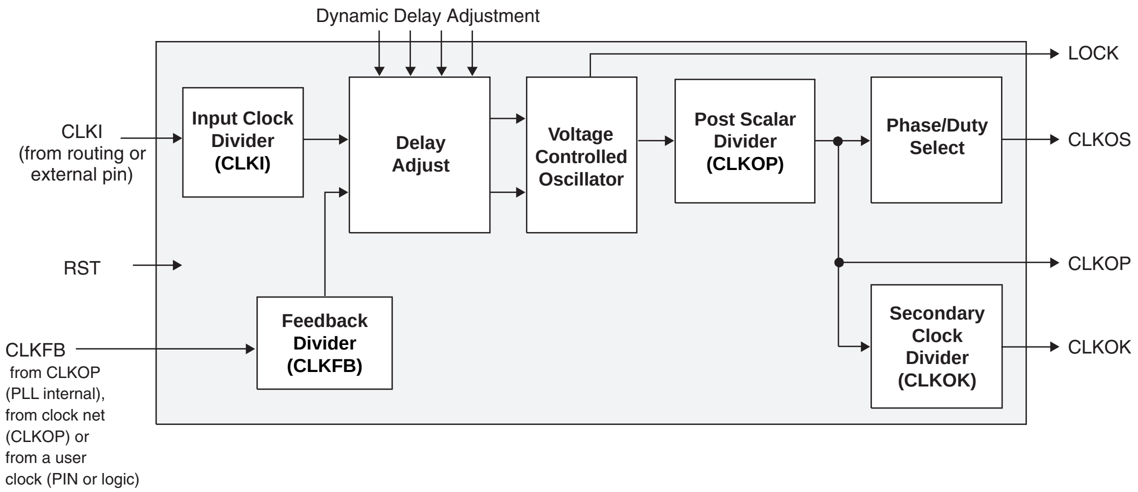


Figure 2-12 shows the available macros for the PLL. Table 2-5 provides signal description of the PLL Block.

Figure 2-12. PLL Primitive

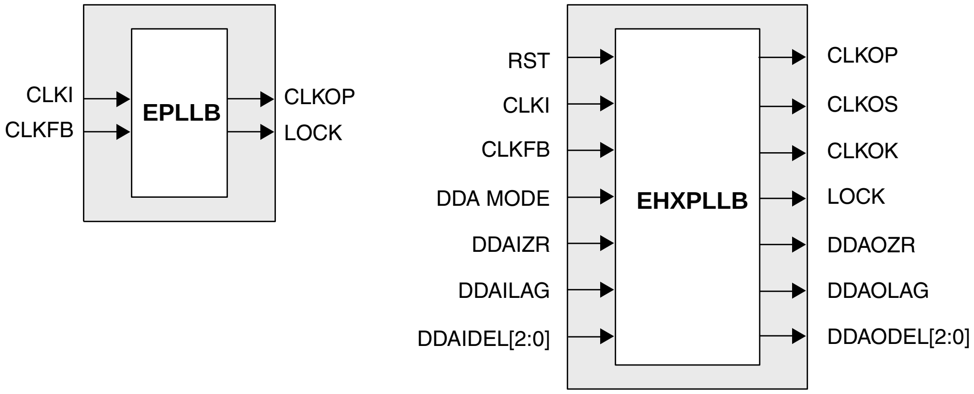
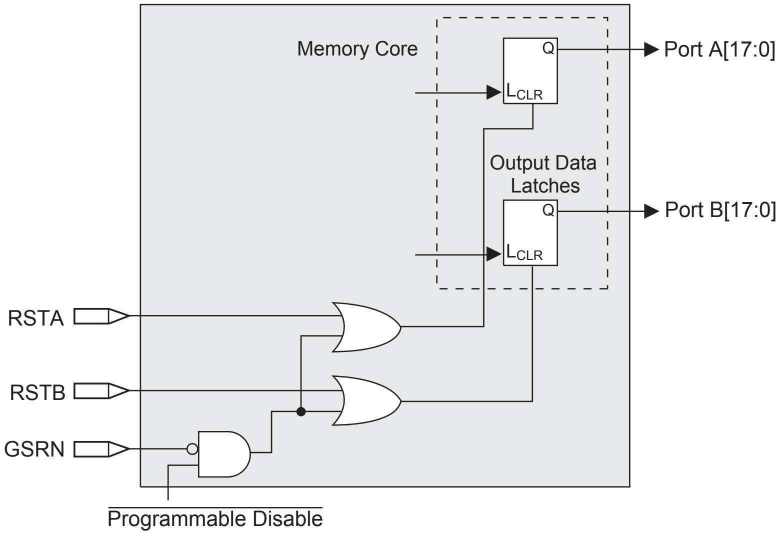


Figure 2-16. Memory Core Reset

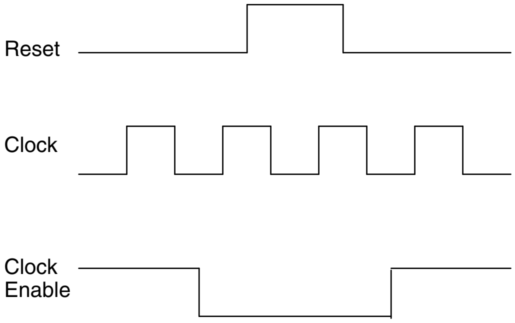


For further information about sysMEM EBR block, please see the the list of technical documentation at the end of this data sheet.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-17. The GSR input to the EBR is always asynchronous.

Figure 2-17. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becomes active.

These instructions apply to all EBR RAM and ROM implementations.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

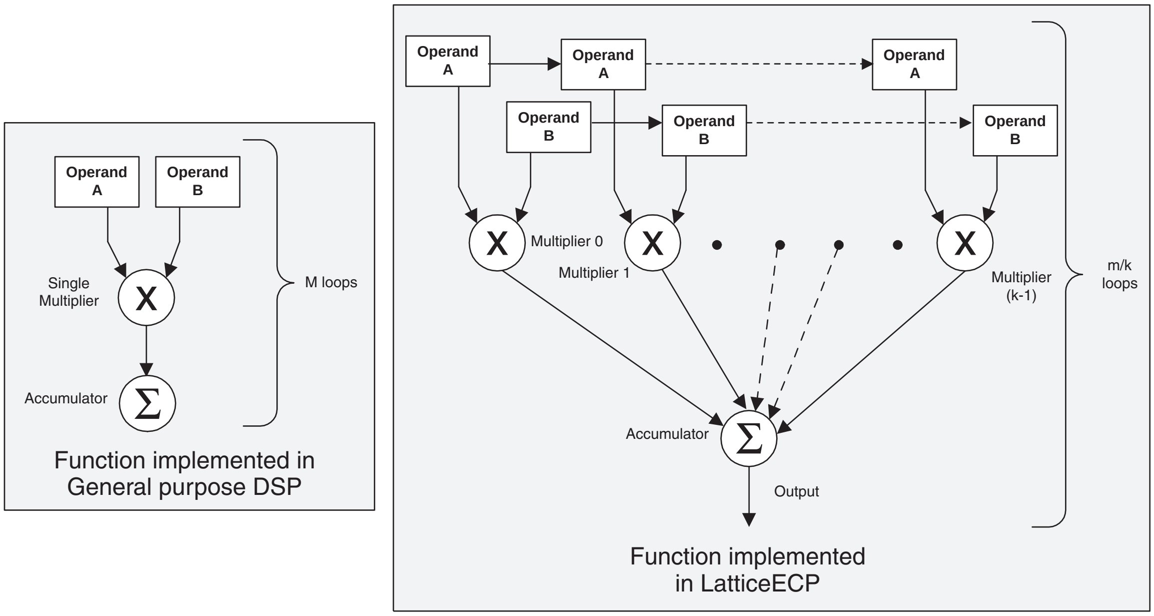
sysDSP Block

The LatticeECP-DSP family provides a sysDSP block, making it ideally suited for low cost, high performance Digital Signal Processing (DSP) applications. Typical functions used in these applications are Finite Impulse Response (FIR) filters; Fast Fourier Transforms (FFT) functions, correlators, Reed-Solomon/Turbo/Convolution encoders and decoders. These complex signal processing functions use similar building blocks such as multiply-adders and multiply-accumulators.

sysDSP Block Approach Compared to General DSP

Conventional general-purpose DSP chips typically contain one to four (Multiply and Accumulate) MAC units with fixed data-width multipliers; this leads to limited parallelism and limited throughput. Their throughput is increased by higher clock speeds. The LatticeECP, on the other hand, has many DSP blocks that support different data-widths. This allows the designer to use highly parallel implementations of DSP functions. The designer can optimize the DSP performance vs. area by choosing an appropriate level of parallelism. Figure 2-18 compares the serial and the parallel implementations.

Figure 2-18. Comparison of General DSP and LatticeECP-DSP Approaches



sysDSP Block Capabilities

The sysDSP block in the LatticeECP-DSP family supports four functional elements in three 9, 18 and 36 data path widths. The user selects a function element for a DSP block and then selects the width and type (signed/unsigned) of its operands. The operands in the LatticeECP-DSP family sysDSP Blocks can be either signed or unsigned but not mixed within a function element. Similarly, the operand widths cannot be mixed within a block.

The resources in each sysDSP block can be configured to support the following four elements:

- MULT (Multiply)
- MAC (Multiply, Accumulate)
- MULTADD (Multiply, Addition/Subtraction)
- MULTADDSUM (Multiply, Addition/Subtraction, Accumulate)

The number of elements available in each block depends on the width selected from the three available options x9, x18, and x36. A number of these elements are concatenated for highly parallel implementations of DSP functions. Table 2-1 shows the capabilities of the block.

Signed and Unsigned with Different Widths

The DSP block supports different widths of signed and unsigned multipliers besides x9, x18 and x36 widths. For unsigned operands, unused upper data bits should be filled to create a valid x9, x18 or x36 operand. For signed two's complement operands, sign extension of the most significant bit should be performed until x9, x18 or x36 width is reached. Table 2-8 provides an example of this.

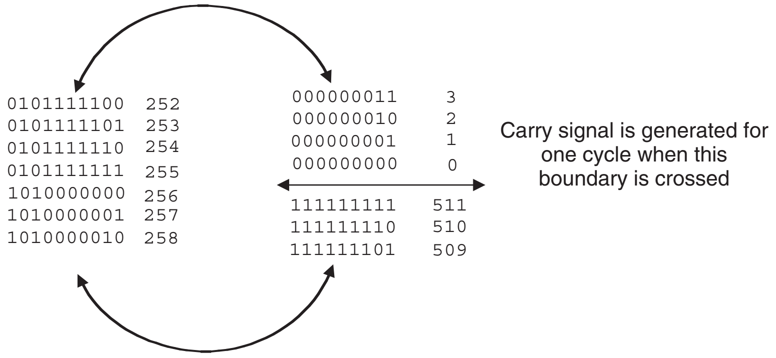
Table 2-8. An Example of Sign Extension

Number	Unsigned	Unsigned 9-bit	Unsigned 18-bit	Signed	Two's Complement Signed 9-Bits	Two's Complement Signed 18-bits
+5	0101	000000101	000000000000000101	0101	000000101	000000000000000101
-6	0110	000000110	000000000000000110	1010	111111010	111111111111111010

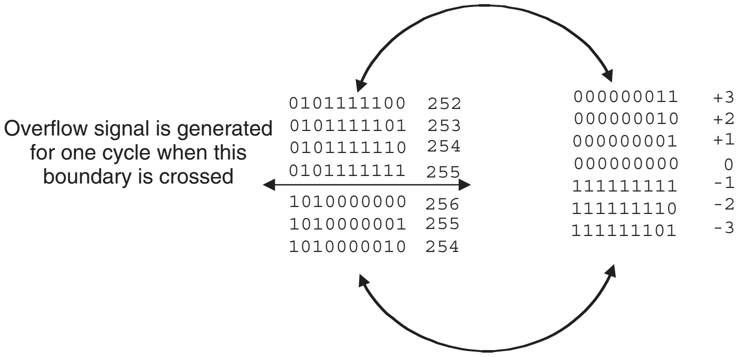
OVERFLOW Flag from MAC

The sysDSP block provides an overflow output to indicate that the accumulator has overflowed. When two unsigned numbers are added and the result is a smaller number then accumulator roll over is said to occur and overflow signal is indicated. When two positive numbers are added with a negative sum and when two negative numbers are added with a positive sum, then the accumulator "roll-over" is said to have occurred and an overflow signal is indicated. Note when overflow occurs the overflow flag is present for only one cycle. By counting these overflow pulses in FPGA logic, larger accumulators can be constructed. The conditions overflow signals for signed and unsigned operands are listed in Figure 2-23.

Figure 2-23. Accumulator Overflow/Underflow Conditions



Unsigned Operation



Signed Operation

IPexpress™

The user can access the sysDSP block via the IPexpress configuration tool, included with the ispLEVER design tool suite. IPexpress has options to configure each DSP module (or group of modules) or through direct HDL instantiation. Additionally Lattice has partnered Mathworks to support instantiation in the Simulink tool, which is a Graphical Simulation Environment. Simulink works with ispLEVER and dramatically shortens the DSP design cycle in Lattice FPGAs.

Optimized DSP Functions

Lattice provides a library of optimized DSP IP functions. Some of the IPs planned for LatticeECP DSP are: Bit Correlators, Fast Fourier Transform, Finite Impulse Response (FIR) Filter, Reed-Solomon Encoder/ Decoder, Turbo Encoder/Decoders and Convolutional Encoder/Decoder. Please contact Lattice to obtain the latest list of available DSP IPs.

Resources Available in the LatticeECP Family

Table 2-9 shows the maximum number of multipliers for each member of the LatticeECP family. Table 2-10 shows the maximum available EBR RAM Blocks in each of the LatticeECP family. EBR blocks, together with Distributed RAM can be used to store variables locally for the fast DSP operations.

Table 2-9. Number of DSP Blocks in LatticeECP Family

Device	DSP Block	9x9 Multiplier	18x18 Multiplier	36x36 Multiplier
LFECP6	4	32	16	4
LFECP10	5	40	20	5
LFECP15	6	48	24	6
LFECP20	7	56	28	7
LFECP33	8	64	32	8

Table 2-10. Embedded SRAM in LatticeECP Family

Device	EBR SRAM Block	Total EBR SRAM (Kbits)
LFECP6	10	92
LFECP10	30	276
LFECP15	38	350
LFECP20	46	424
LFECP33	54	498

DSP Performance of the LatticeECP Family

Table 2-11 lists the maximum performance in millions of MAC operations per second (MMAC) for each member of the LatticeECP family.

Table 2-11. DSP Block Performance of LatticeECP Family

Device	DSP Block	DSP Performance MMAC
LFECP6	4	3680
LFECP10	5	4600
LFECP15	6	5520
LFECP20	7	6440
LFECP33	8	7360

Oscillator

Every LatticeECP/EC device has an internal CMOS oscillator which is used to derive a master clock for configuration. The oscillator and the master clock run continuously. The default value of the master clock is 2.5MHz. Table 2-15 lists all the available Master Clock frequencies. When a different Master Clock is selected during the design process, the following sequence takes place:

1. User selects a different Master Clock frequency.
2. During configuration the device starts with the default (2.5MHz) Master Clock frequency.
3. The clock configuration settings are contained in the early configuration bit stream.
4. The Master Clock frequency changes to the selected frequency once the clock configuration bits are received.

For further information about the use of this oscillator for configuration, please see the list of technical documentation at the end of this data sheet.

Table 2-15. Selectable Master Clock (CCLK) Frequencies During Configuration

CCLK (MHz)	CCLK (MHz)	CCLK (MHz)
2.5*	13	45
4.3	15	51
5.4	20	55
6.9	26	60
8.1	30	130
9.2	34	—
10.0	41	—

Density Shifting

The LatticeECP/EC family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply Current	LFEC1	6	mA
		LFEC3	10	mA
		LFECP6/LFEC6	15	mA
		LFECP10/LFEC10	25	mA
		LFECP15/LFEC15	35	mA
		LFECP20/LFEC20	60	mA
		LFECP33/LFEC33	85	mA
I_{CCAUX}	Auxiliary Power Supply Current		15	mA
I_{CCPLL}	PLL Power Supply Current		5	mA
I_{CCIO}	Bank Power Supply Current[6]		2	mA
I_{CCJ}	V_{CCJ} Power Supply Current		5	mA

1. For further information about supply current, please see the list of technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
3. Frequency 0MHz.
4. Pattern represents a “blank” configuration data file.
5. T_J=25ºC, power supplies at nominal voltage.
6. Per bank.

sysI/O Recommended Operating Conditions

Standard	V_{CCIO}			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3	3.135	3.3	3.465	—	—	—
LVCMOS 2.5	2.375	2.5	2.625	—	—	—
LVCMOS 1.8	1.71	1.8	1.89	—	—	—
LVCMOS 1.5	1.425	1.5	1.575	—	—	—
LVCMOS 1.2	1.14	1.2	1.26	—	—	—
LVTTL	3.135	3.3	3.465	—	—	—
PCI	3.135	3.3	3.465	—	—	—
SSTL18 Class I	1.71	1.8	1.89	0.833	0.90	0.969
SSTL2 Class I, II	2.375	2.5	2.625	1.15	1.25	1.35
SSTL3 Class I, II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL15 Class I	1.425	1.5	1.575	0.68	0.75	0.9
HSTL15 Class III	1.425	1.5	1.575	—	0.9	—
HSTL 18 Class I, II	1.71	1.8	1.89	—	0.9	—
HSTL 18 Class III	1.71	1.8	1.89	—	1.08	—
LVDS	2.375	2.5	2.625	—	—	—
LVPECL[1]	3.135	3.3	3.465	—	—	—
BLVDS[1]	2.375	2.5	2.625	—	—	—
RSDS[1]	2.375	2.5	2.625	—	—	—

1. Outputs are implemented with the addition of external resistors. V_{CCIO} applies to outputs only.

LatticeECP/EC External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Primary Clock without PLL)[1]									
t_{CO}[7]	Clock to Output - PIO Output Register	LFEC1	—	5.09	—	6.11	—	7.13	ns
		LFEC3	—	5.71	—	6.85	—	7.99	ns
		LFEC6	—	5.60	—	6.72	—	7.84	ns
		LFEC10	—	5.47	—	6.57	—	7.66	ns
		LFEC15	—	5.67	—	6.81	—	7.94	ns
		LFEC20	—	5.89	—	7.07	—	8.25	ns
		LFEC33	—	6.19	—	7.42	—	8.66	ns
t_{SU}[7]	Clock to Data Setup - PIO Input Register	LFEC1	-0.08	—	-0.10	—	-0.12	—	ns
		LFEC3	-0.70	—	-0.84	—	-0.98	—	ns
		LFEC6	-0.63	—	-0.76	—	-0.89	—	ns
		LFEC10	-0.43	—	-0.52	—	-0.61	—	ns
		LFEC15	-0.70	—	-0.84	—	-0.98	—	ns
		LFEC20	-0.88	—	-1.06	—	-1.24	—	ns
		LFEC33	-1.12	—	-1.34	—	-1.56	—	ns
t_{H}[7]	Clock to Data Hold - PIO Input Register	LFEC1	2.19	—	2.62	—	3.06	—	ns
		LFEC3	2.80	—	3.36	—	3.92	—	ns
		LFEC6	2.69	—	3.23	—	3.77	—	ns
		LFEC10	2.56	—	3.08	—	3.59	—	ns
		LFEC15	2.76	—	3.32	—	3.87	—	ns
		LFEC20	2.99	—	3.58	—	4.18	—	ns
		LFEC33	3.28	—	3.93	—	4.59	—	ns
t_{SU_DEL}[7]	Clock to Data Setup - PIO Input Register with Data Input Delay	LFEC1	3.36	—	4.03	—	4.70	—	ns
		LFEC3	2.74	—	3.29	—	3.84	—	ns
		LFEC6	2.81	—	3.37	—	3.93	—	ns
		LFEC10	3.01	—	3.61	—	4.21	—	ns
		LFEC15	2.74	—	3.29	—	3.83	—	ns
		LFEC20	2.56	—	3.07	—	3.58	—	ns
		LFEC33	2.32	—	2.79	—	3.25	—	ns
tH_DEL[7]	Clock to Data Hold - PIO Input Register with Input Data Delay	LFEC1	-1.31	—	-1.57	—	-1.83	—	ns
		LFEC3	-0.70	—	-0.83	—	-0.97	—	ns
		LFEC6	-0.80	—	-0.96	—	-1.12	—	ns
		LFEC10	-0.93	—	-1.12	—	-1.30	—	ns
		LFEC15	-0.73	—	-0.88	—	-1.02	—	ns
		LFEC20	-0.51	—	-0.61	—	-0.71	—	ns
		LFEC33	-0.22	—	-0.26	—	-0.30	—	ns
f_{MAX_IO}[2]	Clock Frequency of I/O and PFU Register	All	—	420	—	378	—	340	Mhz
DDR I/O Pin Parameters[3, 4, 5]									
t_{DVADQ}	Data Valid After DQS (DDR Read)	All	—	0.19	—	0.19	—	0.19	UI
t_{DVEDQ}	Data Hold After DQS (DDR Read)	All	0.67	—	0.67	—	0.67	—	UI

LatticeECP/EC External Switching Characteristics (Continued)

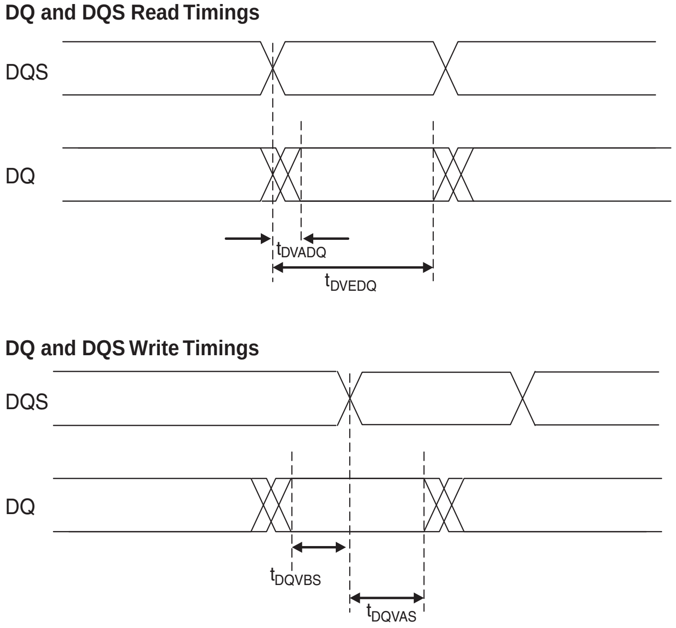
Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{DQVBS}	Data Valid Before DQS	All	0.20	—	0.20	—	0.20	—	UI
t_{DQVAS}	Data Valid After DQS	All	0.20	—	0.20	—	0.20	—	UI
f_{MAX_DDR}	DDR Clock Frequency	All	95	200	95	166	95	133	MHz
Primary and Secondary Clock[6]									
f_{MAX_PRI}[2]	Frequency for Primary Clock Tree	All	—	420	—	378	—	340	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	All	1.19	—	1.19	—	1.19	—	ns
t_{SKEW_PRI}	Primary Clock Skew within an I/O Bank	All	—	250	—	300	—	350	ps

1. General timing numbers based on LVCMOS2.5V, 12 mA. Loading of 0 pF.
2. Using LVDS I/O standard.
3. DDR timing numbers based on SSTL I/O.
4. DDR specifications are characterized but not tested.
5. UI is average bit period.
6. Based on a single primary clock.
7. These timing numbers were generated using ispLEVER design tool. Exact performance may vary with design and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

Timing v.G 0.30

Figure 3-5. DDR Timings



LatticeECP/EC Family Timing Adders[1, 2, 3]

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25	LVDS	0.41	0.50	0.58	ns
BLVDS25	BLVDS	0.41	0.50	0.58	ns
LVPECL33	LVPECL	0.50	0.60	0.70	ns
HSTL18_I	HSTL_18 class I	0.41	0.49	0.57	ns
HSTL18_II	HSTL_18 class II	0.41	0.49	0.57	ns
HSTL18_III	HSTL_18 class III	0.41	0.49	0.57	ns
HSTL18D_I	Differential HSTL 18 class I	0.37	0.44	0.52	ns
HSTL18D_II	Differential HSTL 18 class II	0.37	0.44	0.52	ns
HSTL18D_III	Differential HSTL 18 class III	0.37	0.44	0.52	ns
HSTL15_I	HSTL_15 class I	0.40	0.48	0.56	ns
HSTL15_III	HSTL_15 class III	0.40	0.48	0.56	ns
HSTL15D_I	Differential HSTL 15 class I	0.37	0.44	0.51	ns
HSTL15D_III	Differential HSTL 15 class III	0.37	0.44	0.51	ns
SSTL33_I	SSTL_3 class I	0.46	0.55	0.64	ns
SSTL33_II	SSTL_3 class II	0.46	0.55	0.64	ns
SSTL33D_I	Differential SSTL_3 class I	0.39	0.47	0.55	ns
SSTL33D_II	Differential SSTL_3 class II	0.39	0.47	0.55	ns
SSTL25_I	SSTL_2 class I	0.43	0.51	0.60	ns
SSTL25_II	SSTL_2 class II	0.43	0.51	0.60	ns
SSTL25D_I	Differential SSTL_2 class I	0.38	0.45	0.53	ns
SSTL25D_II	Differential SSTL_2 class II	0.38	0.45	0.53	ns
SSTL18_I	SSTL_18 class I	0.40	0.48	0.56	ns
SSTL18D_I	Differential SSTL_18 class I	0.37	0.44	0.51	ns
LVTTL33	LVTTL	0.07	0.09	0.10	ns
LVCMOS33	LVCMOS 3.3	0.07	0.09	0.10	ns
LVCMOS25	LVCMOS 2.5	0.00	0.00	0.00	ns
LVCMOS18	LVCMOS 1.8	0.07	0.09	0.10	ns
LVCMOS15	LVCMOS 1.5	0.24	0.29	0.33	ns
LVCMOS12	LVCMOS 1.2	1.27	1.52	1.77	ns
PCI33	PCI	0.07	0.09	0.10	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	0.12	0.14	0.17	ns
LVDS25	LVDS 2.5	-0.44	-0.53	-0.62	ns
BLVDS25	BLVDS 2.5	0.33	0.40	0.46	ns
LVPECL33	LVPECL 3.3	0.20	0.24	0.28	ns
HSTL18_I	HSTL_18 class I	-0.10	-0.12	-0.14	ns
HSTL18_II	HSTL_18 class II	0.06	0.07	0.08	ns
HSTL18_III	HSTL_18 class III	0.15	0.19	0.22	ns
HSTL18D_I	Differential HSTL 18 class I	-0.10	-0.12	-0.14	ns
HSTL18D_II	Differential HSTL 18 class II	0.06	0.07	0.08	ns
HSTL18D_III	Differential HSTL 18 class III	0.15	0.19	0.22	ns
HSTL15_I	HSTL_15 class I	0.08	0.10	0.11	ns

LFECP/EC10 and LFECP/EC15 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFECP10/LFEC10				LFECP15/LFEC15			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
A10	PT25B	0	C	PCLKC0_0	PT25B	0	C	PCLKC0_0
GND	GND0	0			GND0	0		
B10	PT25A	0	T	PCLKT0_0	PT25A	0	T	PCLKT0_0
C9	PT24B	0	C	VREF1_0	PT24B	0	C	VREF1_0
B9	PT24A	0	T	VREF2_0	PT24A	0	T	VREF2_0
E9	PT23B	0	C		PT23B	0	C	
D9	PT23A	0	T		PT23A	0	T	
D8	PT22B	0	C		PT22B	0	C	
C8	PT22A	0	T	TDQS22	PT22A	0	T	TDQS22
A9	PT21B	0	C		PT21B	0	C	
GND	GND0	0			GND0	0		
A8	PT21A	0	T		PT21A	0	T	
B8	PT20B	0	C		PT20B	0	C	
B7	PT20A	0	T		PT20A	0	T	
D7	PT19B	0	C		PT19B	0	C	
C7	PT19A	0	T		PT19A	0	T	
A7	PT18B	0	C		PT18B	0	C	
A6	PT18A	0	T		PT18A	0	T	
E7	PT17B	0	C		PT17B	0	C	
GND	GND0	0			GND0	0		
E6	PT17A	0	T		PT17A	0	T	
D6	PT16B	0	C		PT16B	0	C	
C6	PT16A	0	T		PT16A	0	T	
B6	PT15B	0	C		PT15B	0	C	
B5	PT15A	0	T		PT15A	0	T	
A5	PT14B	0	C		PT14B	0	C	
A4	PT14A	0	T	TDQS14	PT14A	0	T	TDQS14
A3	PT13B	0	C		PT13B	0	C	
-	GND0	0			GND0	0		
A2	PT13A	0	T		PT13A	0	T	
B2	PT12B	0	C		PT12B	0	C	
B3	PT12A	0	T		PT12A	0	T	
D5	PT11B	0	C		PT11B	0	C	
C5	PT11A	0	T		PT11A	0	T	
C4	PT10B	0	C		PT10B	0	C	
B4	PT10A	0	T		PT10A	0	T	
GND	GND0	0			GND0	0		
GND	GND0	0			GND0	0		
A1	GND	-			GND	-		
A16	GND	-			GND	-		
G10	GND	-			GND	-		
G7	GND	-			GND	-		
G8	GND	-			GND	-		

LFECP/EC6, LFECP/EC10, LFECP/EC15 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP6/LFEC6					LFECP10/LFEC10					LFECP/LFEC15				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
M4	PL13A	6	T		M4	PL22A	6	T		M4	PL26A	6	T	
M5	PL13B	6	C		M5	PL22B	6	C		M5	PL26B	6	C	
M1	PL14A	6	T		M1	PL23A	6	T		M1	PL27A	6	T	
GND	GND6	6			GND	GND6	6			GND	GND6	6		
M2	PL14B	6	C		M2	PL23B	6	C		M2	PL27B	6	C	
N3	PL15A	6	T	LDQS15	N3	PL24A	6	T	LDQS24	N3	PL28A	6	T	LDQS28
M3	PL15B	6	C		M3	PL24B	6	C		M3	PL28B	6	C	
N5	PL16A	6	T		N5	PL25A	6	T		N5	PL29A	6	T	
N4	PL16B	6	C		N4	PL25B	6	C		N4	PL29B	6	C	
N1	PL17A	6	T		N1	PL26A	6	T		N1	PL30A	6	T	
N2	PL17B	6	C		N2	PL26B	6	C		N2	PL30B	6	C	
P1	PL18A	6	T		P1	PL27A	6	T		P1	PL31A	6	T	
GND	GND6	6			GND	GND6	6			GND	GND6	6		
P2	PL18B	6	C		P2	PL27B	6	C		P2	PL31B	6	C	
R6	NC	-			R6	NC	-			R6	PL32A	6	T	
P5	NC	-			P5	NC	-			P5	PL32B	6	C	
P3	NC	-			P3	NC	-			P3	PL33A	6	T	
P4	NC	-			P4	NC	-			P4	PL33B	6	C	
R1	NC	-			R1	NC	-			R1	PL34A	6	T	
R2	NC	-			R2	NC	-			R2	PL34B	6	C	
R5	NC	-			R5	NC	-			R5	PL35A	6	T	
GND	-	-			-	-	-			GND	GND6	6		
R4	NC	-			R4	NC	-			R4	PL35B	6	C	
T1	NC	-			T1	NC	-			T1	NC	-		
T2	NC	-			T2	NC	-			T2	NC	-		
R3	NC	-			R3	NC	-			R3	NC	-		
T3	NC	-			T3	NC	-			T3	NC	-		
T5	TCK	6			T5	TCK	6			T5	TCK	6		
U5	TDI	6			U5	TDI	6			U5	TDI	6		
T4	TMS	6			T4	TMS	6			T4	TMS	6		
U1	TDO	6			U1	TDO	6			U1	TDO	6		
U2	VCCJ	6			U2	VCCJ	6			U2	VCCJ	6		
V1	PL20A	6	T	LLM0_PLLT_IN_A	V1	PL29A	6	T	LLM0_PLLT_IN_A	V1	PL37A	6	T	LLM0_PLLT_IN_A
V2	PL20B	6	C	LLM0_PLLC_IN_A	V2	PL29B	6	C	LLM0_PLLC_IN_A	V2	PL37B	6	C	LLM0_PLLC_IN_A
U3	PL21A	6	T	LLM0_PLLT_FB_A	U3	PL30A	6	T	LLM0_PLLT_FB_A	U3	PL38A	6	T	LLM0_PLLT_FB_A
V3	PL21B	6	C	LLM0_PLLC_FB_A	V3	PL30B	6	C	LLM0_PLLC_FB_A	V3	PL38B	6	C	LLM0_PLLC_FB_A
U4	PL22A	6	T		U4	PL31A	6	T		U4	PL39A	6	T	
V5	PL22B	6	C		V5	PL31B	6	C		V5	PL39B	6	C	
W1	PL23A	6	T		W1	PL32A	6	T		W1	PL40A	6	T	
GND	GND6	6			GND	GND6	6			GND	GND6	6		
W2	PL23B	6	C		W2	PL32B	6	C		W2	PL40B	6	C	
Y1	PL24A	6	T	LDQS24	Y1	PL33A	6	T	LDQS33	Y1	PL41A	6	T	LDQS41
Y2	PL24B	6	C		Y2	PL33B	6	C		Y2	PL41B	6	C	
AA1	PL25A	6	T		AA1	PL34A	6	T		AA1	PL42A	6	T	
AA2	PL25B	6	C		AA2	PL34B	6	C		AA2	PL42B	6	C	
W4	PL26A	6	T		W4	PL35A	6	T		W4	PL43A	6	T	
V4	PL26B	6	C		V4	PL35B	6	C		V4	PL43B	6	C	
W3	PL27A	6	T	VREF1_6	W3	PL36A	6	T	VREF1_6	W3	PL44A	6	T	VREF1_6
Y3	PL27B	6	C	VREF2_6	Y3	PL36B	6	C	VREF2_6	Y3	PL44B	6	C	VREF2_6
GND	GND6	6			GND	GND6	6			GND	GND6	6		

LFECP/EC6, LFECP/EC10, LFECP/EC15 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP6/LFEC6					LFECP10/LFEC10					LFECP/LFEC15				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
C21	NC	-			C21	PR5B	2	C		C21	PR5B	2	C	
C20	NC	-			C20	PR5A	2	T		C20	PR5A	2	T	
F18	NC	-			F18	PR4B	2	C		F18	PR4B	2	C	
E18	NC	-			E18	PR4A	2	T		E18	PR4A	2	T	
B22	NC	-			B22	PR3B	2	C		B22	PR3B	2	C	
B21	NC	-			B21	PR3A	2	T		B21	PR3A	2	T	
E19	PR2B	2	C	VREF1_2	E19	PR2B	2	C	VREF1_2	E19	PR2B	2	C	VREF1_2
D19	PR2A	2	T	VREF2_2	D19	PR2A	2	T	VREF2_2	D19	PR2A	2	T	VREF2_2
GND	GND2	2			GND	GND2	2			GND	GND2	2		
GND	GND1	1			GND	GND1	1			GND	GND1	1		
G17	NC	-			G17	NC	-			G17	PT49B	1	C	
F17	NC	-			F17	NC	-			F17	PT49A	1	T	
D18	NC	-			D18	NC	-			D18	PT48B	1	C	
C18	NC	-			C18	NC	-			C18	PT48A	1	T	
C19	NC	-			C19	NC	-			C19	PT47B	1	C	
B20	NC	-			B20	NC	-			B20	PT47A	1	T	
D17	NC	-			D17	NC	-			D17	PT46B	1	C	
C16	NC	-			C16	NC	-			C16	PT46A	1	T	TDQS46
B19	NC	-			B19	NC	-			B19	PT45B	1	C	
GND	-	-			GND	-	-			GND	GND1	1		
A20	NC	-			A20	NC	-			A20	PT45A	1	T	
E17	NC	-			E17	NC	-			E17	PT44B	1	C	
C17	NC	-			C17	NC	-			C17	PT44A	1	T	
F16	NC	-			F16	NC	-			F16	PT43B	1	C	
E16	NC	-			E16	NC	-			E16	PT43A	1	T	
F15	NC	-			F15	NC	-			F15	PT42B	1	C	
D16	NC	-			D16	NC	-			D16	PT42A	1	T	
B18	PT33B	1	C		B18	PT41B	1	C		B18	PT41B	1	C	
GND	-	-			GND	-	-			GND	GND1	1		
A19	PT33A	1	T		A19	PT41A	1	T		A19	PT41A	1	T	
B17	PT32B	1	C		B17	PT40B	1	C		B17	PT40B	1	C	
A18	PT32A	1	T		A18	PT40A	1	T		A18	PT40A	1	T	
B16	PT31B	1	C		B16	PT39B	1	C		B16	PT39B	1	C	
A17	PT31A	1	T		A17	PT39A	1	T		A17	PT39A	1	T	
B15	PT30B	1	C		B15	PT38B	1	C		B15	PT38B	1	C	
A16	PT30A	1	T	TDQS30	A16	PT38A	1	T	TDQS38	A16	PT38A	1	T	TDQS38
A15	PT29B	1	C		A15	PT37B	1	C		A15	PT37B	1	C	
GND	GND1	1			GND	GND1	1			GND	GND1	1		
A14	PT29A	1	T		A14	PT37A	1	T		A14	PT37A	1	T	
G14	PT28B	1	C		G14	PT36B	1	C		G14	PT36B	1	C	
E15	PT28A	1	T		E15	PT36A	1	T		E15	PT36A	1	T	
D15	PT27B	1	C		D15	PT35B	1	C		D15	PT35B	1	C	
C15	PT27A	1	T		C15	PT35A	1	T		C15	PT35A	1	T	
C14	PT26B	1	C		C14	PT34B	1	C		C14	PT34B	1	C	
B14	PT26A	1	T		B14	PT34A	1	T		B14	PT34A	1	T	
A13	PT25B	1	C		A13	PT33B	1	C		A13	PT33B	1	C	
GND	GND1	1			GND	GND1	1			GND	GND1	1		
B13	PT25A	1	T		B13	PT33A	1	T		B13	PT33A	1	T	
E14	PT24B	1	C		E14	PT32B	1	C		E14	PT32B	1	C	
C13	PT24A	1	T		C13	PT32A	1	T		C13	PT32A	1	T	

LFECP/EC20 and LFECP/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP20/LFEC20					LFECP/LFEC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
Y13	PB40A	4	T		Y13	PB40A	4	T	
V14	PB40B	4	C	D5/SPID2	V14	PB40B	4	C	D5/SPID2
AA13	PB41A	4	T		AA13	PB41A	4	T	
GND	GND4	4			GND	GND4	4		
AB13	PB41B	4	C	D6/SPID1	AB13	PB41B	4	C	D6/SPID1
AA14	PB42A	4	T		AA14	PB42A	4	T	
Y14	PB42B	4	C		Y14	PB42B	4	C	
Y15	PB43A	4	T		Y15	PB43A	4	T	
W15	PB43B	4	C		W15	PB43B	4	C	
V15	PB44A	4	T		V15	PB44A	4	T	
T14	PB44B	4	C		T14	PB44B	4	C	
AB14	PB45A	4	T		AB14	PB45A	4	T	
GND	GND4	4			GND	GND4	4		
AB15	PB45B	4	C		AB15	PB45B	4	C	
AB16	PB46A	4	T	BDQS46	AB16	PB46A	4	T	BDQS46
AA15	PB46B	4	C		AA15	PB46B	4	C	
AB17	PB47A	4	T		AB17	PB47A	4	T	
AA16	PB47B	4	C		AA16	PB47B	4	C	
AB18	PB48A	4	T		AB18	PB48A	4	T	
AA17	PB48B	4	C		AA17	PB48B	4	C	
AB19	PB49A	4	T		AB19	PB49A	4	T	
GND	GND4	4			GND	GND4	4		
AA18	PB49B	4	C		AA18	PB49B	4	C	
W16	PB50A	4	T		W16	PB50A	4	T	
U15	PB50B	4	C		U15	PB50B	4	C	
V16	PB51A	4	T		V16	PB51A	4	T	
U16	PB51B	4	C		U16	PB51B	4	C	
Y17	PB52A	4	T		Y17	PB52A	4	T	
V17	PB52B	4	C		V17	PB52B	4	C	
AB20	PB53A	4	T		AB20	PB53A	4	T	
GND	GND4	4			GND	GND4	4		
AA19	PB53B	4	C		AA19	PB53B	4	C	
Y16	PB54A	4	T	BDQS54	Y16	PB54A	4	T	BDQS54
W17	PB54B	4	C		W17	PB54B	4	C	
AA20	PB55A	4	T		AA20	PB55A	4	T	
Y19	PB55B	4	C		Y19	PB55B	4	C	
Y18	PB56A	4	T		Y18	PB56A	4	T	
W18	PB56B	4	C		W18	PB56B	4	C	
T17	PB57A	4	T		T17	PB57A	4	T	
U17	PB57B	4	C		U17	PB57B	4	C	
GND	-	-			GND	GND4	4		
GND	GND4	4			GND	GND4	4		
GND	GND3	3			GND	GND4	4		
GND	-	-			GND	GND3	3		

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
L24	PR17A	2	T		L24	PR29A	2	T	
K25	PR16B	2	C		K25	PR28B	2	C	
J25	PR16A	2	T		J25	PR28A	2	T	
J26	PR15B	2	C		J26	PR27B	2	C	
H26	PR15A	2	T		H26	PR27A	2	T	
H25	PR14B	2	C		H25	PR26B	2	C	
GND	GND2	2			GND	GND2	2		
J24	PR14A	2	T		J24	PR26A	2	T	
K21	PR13B	2	C		K21	PR25B	2	C	
K22	PR13A	2	T		K22	PR25A	2	T	
K20	PR12B	2	C		K20	PR24B	2	C	
J20	PR12A	2	T		J20	PR24A	2	T	
K23	PR11B	2	C		K23	PR23B	2	C	
K24	PR11A	2	T		K24	PR23A	2	T	RDQS23
J21	NC	-			J21	PR22B	2	C	
-	-	-			GND	GND2	2		
J22	NC	-			J22	PR22A	2	T	
J23	NC	-			J23	PR21B	2	C	
H22	NC	-			H22	PR21A	2	T	
G26	NC	-			G26	PR20B	2	C	
F26	NC	-			F26	PR20A	2	T	
E26	NC	-			E26	PR19B	2	C	
E25	NC	-			E25	PR19A	2	T	
F25	PR9B	2	C	RUM0_PLLC_FB_A	F25	PR17B	2	C	RUM0_PLLC_FB_A
GND	GND2	2			GND	GND2	2		
G25	PR9A	2	T	RUM0_PLLT_FB_A	G25	PR17A	2	T	RUM0_PLLT_FB_A
H23	PR8B	2	C	RUM0_PLLC_IN_A	H23	PR16B	2	C	RUM0_PLLC_IN_A
H24	PR8A	2	T	RUM0_PLLT_IN_A	H24	PR16A	2	T	RUM0_PLLT_IN_A
H21	PR7B	2	C		H21	PR15B	2	C	
G21	PR7A	2	T		G21	PR15A	2	T	
D26	PR6B	2	C		D26	PR14B	2	C	
D25	PR6A	2	T	RDQS6	D25	PR14A	2	T	RDQS14
F21	PR5B	2	C		F21	PR13B	2	C	
-	-	-			GND	GND2	2		
G22	PR5A	2	T		G22	PR13A	2	T	
G24	PR4B	2	C		G24	PR12B	2	C	
G23	PR4A	2	T		G23	PR12A	2	T	
C26	PR3B	2	C		C26	PR11B	2	C	
C25	PR3A	2	T		C25	PR11A	2	T	
F24	NC	-			F24	PR9B	2	C	
-	-	-			GND	GND2	2		
F23	NC	-			F23	PR9A	2	T	

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
A5	PT13B	0	C		A5	PT13B	0	C	
GND	GND0	0			GND	GND0	0		
A4	PT13A	0	T		A4	PT13A	0	T	
F9	PT12B	0	C		F9	PT12B	0	C	
B6	PT12A	0	T		B6	PT12A	0	T	
E9	PT11B	0	C		E9	PT11B	0	C	
C8	PT11A	0	T		C8	PT11A	0	T	
G8	PT10B	0	C		G8	PT10B	0	C	
B5	PT10A	0	T		B5	PT10A	0	T	
A3	PT9B	0	C		A3	PT9B	0	C	
GND	GND0	0			GND	GND0	0		
A2	PT9A	0	T		A2	PT9A	0	T	
F8	PT8B	0	C		F8	PT8B	0	C	
B4	PT8A	0	T		B4	PT8A	0	T	
E8	PT7B	0	C		E8	PT7B	0	C	
B3	PT7A	0	T		B3	PT7A	0	T	
D8	PT6B	0	C		D8	PT6B	0	C	
G7	PT6A	0	T	TDQS6	G7	PT6A	0	T	TDQS6
C4	PT5B	0	C		C4	PT5B	0	C	
C5	PT5A	0	T		C5	PT5A	0	T	
E7	PT4B	0	C		E7	PT4B	0	C	
D4	PT4A	0	T		D4	PT4A	0	T	
F7	PT3B	0	C		F7	PT3B	0	C	
D6	PT3A	0	T		D6	PT3A	0	T	
D7	PT2B	0	C		D7	PT2B	0	C	
E6	PT2A	0	T		E6	PT2A	0	T	
GND	GND0	0			GND	GND0	0		
K10	GND	-			K10	GND	-		
K11	GND	-			K11	GND	-		
K12	GND	-			K12	GND	-		
K13	GND	-			K13	GND	-		
K14	GND	-			K14	GND	-		
K15	GND	-			K15	GND	-		
K16	GND	-			K16	GND	-		
L10	GND	-			L10	GND	-		
L11	GND	-			L11	GND	-		
L12	GND	-			L12	GND	-		
L13	GND	-			L13	GND	-		
L14	GND	-			L14	GND	-		
L15	GND	-			L15	GND	-		
L16	GND	-			L16	GND	-		
L17	GND	-			L17	GND	-		

LatticeECP Commercial

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP6E-3F484C	224	-3	fpBGA	484	COM	6.1K
LFECP6E-4F484C	224	-4	fpBGA	484	COM	6.1K
LFECP6E-5F484C	224	-5	fpBGA	484	COM	6.1K
LFECP6E-3F256C	195	-3	fpBGA	256	COM	6.1K
LFECP6E-4F256C	195	-4	fpBGA	256	COM	6.1K
LFECP6E-5F256C	195	-5	fpBGA	256	COM	6.1K
LFECP6E-3Q208C	147	-3	PQFP	208	COM	6.1K
LFECP6E-4Q208C	147	-4	PQFP	208	COM	6.1K
LFECP6E-5Q208C	147	-5	PQFP	208	COM	6.1K
LFECP6E-3T144C	97	-3	TQFP	144	COM	6.1K
LFECP6E-4T144C	97	-4	TQFP	144	COM	6.1K
LFECP6E-5T144C	97	-5	TQFP	144	COM	6.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP10E-3F484C	288	-3	fpBGA	484	COM	10.2K
LFECP10E-4F484C	288	-4	fpBGA	484	COM	10.2K
LFECP10E-5F484C	288	-5	fpBGA	484	COM	10.2K
LFECP10E-3F256C	195	-3	fpBGA	256	COM	10.2K
LFECP10E-4F256C	195	-4	fpBGA	256	COM	10.2K
LFECP10E-5F256C	195	-5	fpBGA	256	COM	10.2K
LFECP10E-3Q208C	147	-3	PQFP	208	COM	10.2K
LFECP10E-4Q208C	147	-4	PQFP	208	COM	10.2K
LFECP10E-5Q208C	147	-5	PQFP	208	COM	10.2K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP15E-3F484C	352	-3	fpBGA	484	COM	15.3K
LFECP15E-4F484C	352	-4	fpBGA	484	COM	15.3K
LFECP15E-5F484C	352	-5	fpBGA	484	COM	15.3K
LFECP15E-3F256C	195	-3	fpBGA	256	COM	15.3K
LFECP15E-4F256C	195	-4	fpBGA	256	COM	15.3K
LFECP15E-5F256C	195	-5	fpBGA	256	COM	15.3K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP20E-3F672C	400	-3	fpBGA	672	COM	19.7K
LFECP20E-4F672C	400	-4	fpBGA	672	COM	19.7K
LFECP20E-5F672C	400	-5	fpBGA	672	COM	19.7K
LFECP20E-3F484C	360	-3	fpBGA	484	COM	19.7K
LFECP20E-4F484C	360	-4	fpBGA	484	COM	19.7K
LFECP20E-5F484C	360	-5	fpBGA	484	COM	19.7K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP33E-3F672C	496	-3	fpBGA	672	COM	32.8K
LFECP33E-4F672C	496	-4	fpBGA	672	COM	32.8K
LFECP33E-5F672C	496	-5	fpBGA	672	COM	32.8K